L Number	Hits	Search Text	DB	Time stamp
1 .	1441	(349/155,156).ccls.	USPAT;	2004/03/30 10:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1609	(427/77,105,106,133).ccls.	USPAT;	2004/03/30 11:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	524	(264/61,272.11).ccls.	USPAT;	2004/03/30 11:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/02/20 44:00
4	2761	438/624.ccls.	USPAT;	2004/03/30 11:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1601	445/24	IBM_TDB	2004/02/20 11:00
5	1601	445/24.ccls.	USPAT;	2004/03/30 11:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
ا م	532	(216/25 22) colo	IBM_TDB USPAT;	2004/03/30 11:00
6	552	(216/25,33).ccls.	US-PGPUB;	2004/03/30 11.00
			EPO; JPO;	
}			DERWENT;	
<u> </u>			IBM_TDB	
7	1190	264/129.ccls.	USPAT;	2004/03/30 11:01
'	1150	201/225100101	US-PGPUB;	200 1,00,00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	341052	spacer	USPAT;	2004/03/30 11:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	723	positive adj mold	USPAT;	2004/03/30 11:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/02/20 11 22
11	142752	photoresist photo-resist photo adj resist	USPAT;	2004/03/30 11:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
12	_	(markling add modd) come (ababanaich ababa markling add markling	IBM_TDB	2004/02/20 44-02
13	7	(positive adj mold) same (photoresist photo-resist photo adj resist)	USPAT;	2004/03/30 11:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
14	0	spacer same ((positive adj mold) near10 (photoresist photo-resist	IBM_TDB USPAT;	2004/03/30 11:02
14	U	photo adj resist))	US-PGPUB;	2007/03/30 11:02
		prioto duj resisciji	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
اا		1	טטו ויוטג	1

	T			2004/22/22 :: ::
15	0	spacer and ((positive adj mold) near10 (photoresist photo-resist	USPAT;	2004/03/30 11:02
		photo adj resist))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	2004/02/20 44:05
12	7	(positive adj mold) near10 (photoresist photo-resist photo adj	USPAT;	2004/03/30 11:05
		resist)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	423828	photograph\$5	USPAT;	2004/03/30 11:05
-			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	,
17	5	(positive adj mold) same photograph\$5	USPAT;	2004/03/30 11:06
			US-PGPUB;	
			EPO; JPO;	
,			DERWENT;	
			IBM_TDB	
18	1095	epoxy adj bisphenol	USPAT;	2004/03/30 11:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	6090	novolac adj resin	USPAT;	2004/03/30 11:06
			US-PGPUB;	
}			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
21	36	(epoxy adj bisphenol) near5 (novolac adj resin)	USPAT;	2004/03/30 11:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	0	(positive adj mold) same ((epoxy adj bisphenol) near5 (novolac	USPAT;	2004/03/30 11:06
		adj resin))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
23	0	(positive adj mold) and ((epoxy adj bisphenol) near5 (novolac adj	USPAT;	2004/03/30 11:07
		resin))	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
24	0	positive near10 ((epoxy adj bisphenol) near5 (novolac adj resin))	USPAT;	2004/03/30 11:07
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
25	15563	positive near10 (photoresist photo-resist photo adj resist)	USPAT;	2004/03/30 11:07
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
27	10	((427/77,105,106,133).ccls.) and (positive near10 (photoresist	USPAT;	2004/03/30 11:07
	1	photo-resist photo adj resist))	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
L			IBM_TDB	

28	1	((264/61,272.11).ccls.) and (positive near10 (photoresist	USPAT;	2004/03/30 11:07
	ļ ·	photo-resist photo adj resist))	US-PGPUB;	
	İ		EPO; JPO;	
			DERWENT;	
		<u> </u>	IBM_TDB	
29	70	438/624.ccls. and (positive near10 (photoresist photo-resist photo	USPAT;	2004/03/30 11:07
		adj resist))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
30	77	445/24.ccls. and (positive near10 (photoresist photo-resist photo	USPAT;	2004/03/30 11:07
		adj resist))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
32	1	264/129.ccls. and (positive near10 (photoresist photo-resist photo	USPAT;	2004/03/30 11:07
		adj resist))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
26	32	((349/155,156).ccls.) and (positive near10 (photoresist	USPAT;	2004/03/30 11:11
		photo-resist photo adj resist))	US-PGPUB;	
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
33	774644	mold	USPAT;	2004/03/30 11:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1	ļ		IBM_TDB	
34	42	mold near10 positive near10 (photoresist photo-resist photo adj	USPAT;	2004/03/30 11:11
"	· -	resist)	US-PGPUB;	
	:	100000	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
35	l o	((349/155,156).ccis.) and (mold near10 positive near10	USPAT;	2004/03/30 11:11
		(photoresist photo-resist photo adj resist))	US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
36	0	((427/77,105,106,133).ccls.) and (mold near10 positive near10	USPAT;	2004/03/30 11:11
	1	(photoresist photo-resist photo adj resist))	US-PGPUB;	, ,
			EPO; JPO;	
	i		DERWENT;	
			IBM_TDB	
37	0	((264/61,272.11).ccls.) and (mold near10 positive near10	USPAT;	2004/03/30 11:11
		(photoresist photo-resist photo adj resist))	US-PGPUB;	
			EPO; JPO;	
}			DERWENT;	
İ			IBM_TDB	
38	0	438/624.ccls. and (mold near10 positive near10 (photoresist	USPAT;	2004/03/30 11:11
		photo-resist photo adj resist))	US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
39	0	445/24.ccls. and (mold near10 positive near10 (photoresist	USPAT;	2004/03/30 11:11
		photo-resist photo adj resist))	US-PGPUB;	,
	-	, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
]		IBM_TDB	

•				
41	0	264/129.ccls. and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB;	2004/03/30 11:12
		prioto realist prioto daj realist,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
40	1	((216/25,33).ccls.) and (mold near10 positive near10 (photoresist	USPAT;	2004/03/30 11:12
	1	photo-resist photo adj resist))	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT; IBM_TDB	
42	16483	sol-gel solgel	USPAT;	2004/03/30 11:12
12	10,03	Sol gel Solger	US-PGPUB;	2001,03,30 11.12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	6	((349/155,156).ccls.) and (sol-gel solgel)	USPAT;	2004/03/30 11:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
44	00	anager came (sel sel selse)	IBM_TDB	2004/02/20 11:12
44	90	spacer same (sol-gel solgel)	USPAT; US-PGPUB;	2004/03/30 11:13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
45	0	((427/77,105,106,133).ccls.) and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
			US-PGPUB;	, ,
			EPO; JPO;	
-			DERWENT;	
4.5		(1004/64 070 44) 1 1 1 1 1 1 1 1 1	IBM_TDB	
46	0	((264/61,272.11).ccls.) and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
47	0	438/624.ccls. and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
		, and the same terms that the same terms the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms that the same terms the same terms that the same terms that the same terms the same terms that the same terms the s	US-PGPUB;	,,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
49	0	((216/25,33).ccls.) and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
50	1	264/129.ccls. and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
			US-PGPUB;	, , ,
			EPO; JPO;	
			DERWENT;	
40	_	445/24 ada and (ana ann anns (a l l l l l l l l	IBM_TDB	2004/02/20 44 15
48	5	445/24.ccls. and (spacer same (sol-gel solgel))	USPAT;	2004/03/30 11:13
*			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
31	37	((216/25,33).ccls.) and (positive near10 (photoresist photo-resist	USPAT;	2004/03/30 11:18
		photo adj resist))	US-PGPUB;	, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
1	1002905	positive	USPAT;	2004/03/30 13:07
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	126567	photoresist	USPAT;	2004/03/30 13:07
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/02/20 42 00
3	1020	epoxy adj bisphenol	USPAT;	2004/03/30 13:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
A	4222	nevelne adi recin	IBM_TDB USPAT;	2004/02/20 12:10
4	4222	novolac adj resin	US-PGPUB;	2004/03/30 13:10
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	35	(epoxy adj bisphenol) near5 (novolac adj resin)	USPAT;	2004/03/30 13:10
		(cpox) adj displicitory ficults (florelide day restity	US-PGPUB;	200 1/05/50 15:10
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
6	257	positive same photoresist same ((epoxy adj bisphenol) (novolac	USPAT;	2004/03/30 13:10
		adj resin))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	341052	spacer	USPAT;	2004/03/30 13:10
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2		IBM_TDB	2004/02/20 12:10
8	2	(positive same photoresist same ((epoxy adj bisphenol) (novolac	USPAT;	2004/03/30 13:10
		adj resin))) same spacer	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
9	13	(positive same photoresist same ((epoxy adj bisphenol) (novolac	USPAT;	2004/03/30 13:22
-	1.5	adj resin))) and spacer	US-PGPUB;	200 1/03/30 13.22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	3220	positive near5 mold	USPAT;	2004/03/30 13:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	1	spacer and ((positive near5 mold) same photoresist)	USPAT;	2004/03/30 13:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
11	24	(nositive nearE mold) same shotoveriet	IBM_TDB	2004/02/20 42:24
11	34	(positive near5 mold) same photoresist	USPAT;	2004/03/30 13:24
			US-PGPUB;	
]			EPO; JPO; DERWENT;	
			IBM_TDB	
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L Number	Hits	Search Text	DB	Time stamp
1	8846	positive near5 photoresist	USPAT;	2004/03/30 14:31
		·	JPO	
2	218550	spacer	USPAT;	2004/03/30 14:31
			JPO	
3	845	(positive near5 photoresist) and spacer	USPAT;	2004/03/30 14:32
			JPO	
4	107	(positive near5 photoresist) same spacer	USPAT;	2004/03/30 14:32
			JPO	
6	341648	mold mould	USPAT;	2004/03/30 14:32
			JPO	
7	18	(positive near5 photoresist) near10 (mold mould)	USPAT;	2004/03/30 14:32
			JPO	2004/02/20 44 47
5	62	(positive near5 photoresist) near10 spacer	USPAT;	2004/03/30 14:47
			JPO	2004/02/20 44:47
8	449	positive adj (mold mould)	USPAT;	2004/03/30 14:47
	_	40 (100) 11 11 11 11 11 11	JPO	2004/02/20 44:40
9	2	spacer near10 (positive adj (mold mould))	USPAT;	2004/03/30 14:49
10	_	(IITO 20000II)	JPO	2004/02/20 14:50
10	05030	("5930890").PN.	USPAT USPAT;	2004/03/30 14:50 2004/03/30 14:51
11	95928	photolithograph\$5	US-PGPUB;	2007/03/30 17.31
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	1	(positive adj (mold mould)) same photolithograph\$5	USPAT;	2004/03/30 14:51
12	•	hosiare adj (mola modia)) same priotolidiographips	US-PGPUB;	==== 1,00,00 = 1.01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	375	photolithograph\$5 near10 (positive near5 photoresist)	USPAT;	2004/03/30 14:52
		English Andrews Control of the Contr	US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	5	spacer same (photolithograph\$5 near10 (positive near5	USPAT;	2004/03/30 14:52
		photoresist))	US-PGPUB;	,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

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		Advand	ced Search: INSPEC -	1969 to date (INZZ)

Search history:

No.	Database	Search term	Info added since	Results	
1	INZZ	positive ADJ (mold OR mould)	unrestricted	3	show titles
2	INZZ	photoresist	unrestricted	7438	show titles
3	INZZ	1 AND 2	unrestricted	0	-
4	INZZ	positive ADJ mold	unrestricted	2	show titles
5	INZZ	2 AND 4	unrestricted	0	-

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	whole document	9	
Information added since: or: none (YYYYMMDD)			search

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- Classification codes A: Physics, 2-3
- Classification codes A: Physics, 4-5
- Classification codes A: Physics, 6
- Classification codes A. Physics, o
- Classification codes A: Physics, 7
- Classification codes A: Physics, 8
- Classification codes A: Physics, 9
- Classification codes B: Electrical & Electronics, 0-5
- Classification codes B: Electrical & Electronics, 6-9
- Classification codes C: Computer & Control, 0-9
- Classification codes D: Information Technology, 0-9
- Treatment codes
- INSPEC sub-file